

DETEX CORPORATION

SHO MISAWA

PHONE: 800-729-3839 EXT.4377

PCB: 106015 PWA: 106016

FAB NOTES:

- 1. THE BOARD HAS TWO LAYERS
- 2. BOARD THICKNESS TO BE 63 MIL
- 3. BOARD TO HAVE 2 OZ CUPPER
- 4. MINIMUM CAD TRACE DIMENSIONS ARE: ____
- 5. PCB SHALL MEET FOLLOWING SPECIFICATIONS/REQUIREMENTS:
 - A. BOARD MATERIAL TO BE NEMA GRADE FR-4 GLASS EPOXY/UL94-VO RATED.
 - B. MANUFACTURER AS PER IPC-6012 AND INSPECT AS PER IPC-A-600.
 - C. PCB IS ROHS COMPLIANT AND MUST SURVIVE LEAD-FREE.
 - D. FINISHED BOARD TO BE SOLDER MASKED OVER BARE COPPER.
 - E. WHITE SILK SCREEN/BLUE SOLDERMASK ON BOTH SIDES.
 - F. BOARD FINISH: ENIG (ELECTROLESS NICKEL IMMERSION GOLD).
 - G. UNLESS OTHERWISE SPECIFIED, ALL HOLES ARE TO BE PLATED THROUGH 0.0011N/(0.025MM) CUPPER MINIMUM.
- 6. REFERENCES TO SYSTEM BOARD SCHEMATIC: UNKNOWN
- 7. 20 MIL V-GROOVE LINES.

REVISION NOTES:

106015 Rev A: Incorporate design from 103845 and 104280 Dual Door PWA's. Add teltale LED's, replace relay with two IPG511's. Ass opto isolators for Status LED's, Pad and Cyl switches. Route all I/O functions onto main connectors to simply wiring.

Rev B: Replace .156 spacing connectors with 3.81mm metric connectors. Fix logic erros on Cyl/Pad opto, add pullup to high side switch

Rev C: Replace 3.81 connectors with separate .200" connectors for each function Retain 3.81 for relay connections for space. clean up power trace routes

Rev D: Add opto for siren drive/isolation.

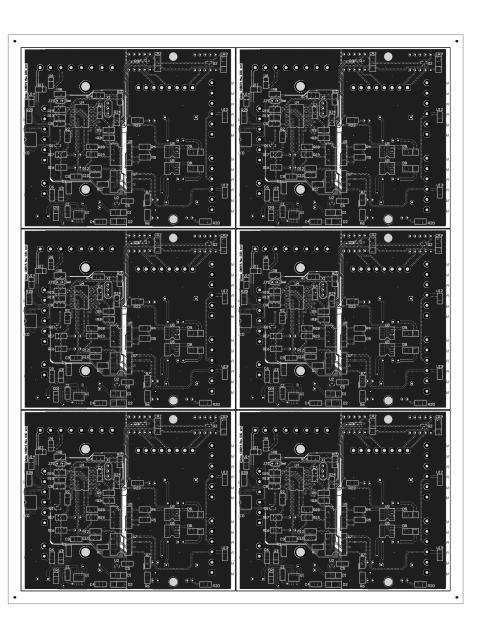
Rev D3: Add TVS to Pad and Cyl inputs. Redo gnd planes for better EMI. Released to proto 06/16/15

Rev D3A: Increase mounting hole tolerance. Make one snap mount oval for REM stud variation.

Rev D3B: Add U14 TVS to 9 volt source for ESD issues.

11.12.2018

Rev D3C: Fixed unconnected ground pad on regulator due to imported design rules.



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FAB NOTES:

- 1. TWO LAYER BOARD
- 2. 64 MIL BOARD THICKNESS
- 3. 2 OZ COPPER POUR, BOTH SIDES
 4. MINIMUM CAD TRACE DIMENSIONS ARE:
- 5. PCB SHALL MEET FOLLOWING SPECIFICATIONS/REQUIREMENTS:
 - A. BOARD MATERIAL TO BE NEMA GRADE FR-4 GLASS EPOXY/UL94-VO RATED
 - B. MANUFACTURER AS PER IPC-6012 AND INSPECT AS PER IPC-A-600
 - C. PCB IS ROHS COMPLIANT AND MUST SURVIVE LEAD-FREE D. FINISHED BOARD TO BE SOLDER MASKED OVER BARE COPPER

 - E. BLUE SOLDER MASK / WHITE SILK SCREENS ON BOTH SIDES F. BOARD FINISH: ENIG (ELECTROLESS NICKEL IMMERSION GOLD)
- G. UNLESS OTHERWISE SPECIFIED, ALL HOLES ARE TO BE PLATED THROUGH 0.001IN/(0.025MM) COPPER MINIMUM 6. REFERENCES TO SYSTEM BOARD SCHEMATIC: 106015SCH 7. 20 MIL SCOUR LINES (+/- 3MIL)

REVISION NOTES:

- 106015 Rev A: Incorporate design from 103845 and 104280 Dual Door PWA's.
 - Add teltale LED's, replace relay with two IPG511's. Ass opto isolators for Status LED's, Pad and Cyl switches. Route all I/O functions onto main
 - connectors to simply wiring.
 - Rev B: Replace .156 spacing connectors with 3.81mm metric connectors. Fix
 - logic erros on Cyl/Pad opto, add pullup to high side switch
 - Rev C: Replace 3.81 connectors with separate .200 connectors for each function Retain 3.81 for relay connections for space. clean up power trace routes
 - Rev D: Add opto for siren drive/isolation.
 - 06/16/15
 - Rev D3: Add TVS to Pad and Cyl inputs. Redo gnd planes for better EMI. Released to proto Rev D3A: Increase mounting hole tolerance. Make one snap mount oval for REM stud variation.
 - Rev D3A:
 - Rev D3B: Add U14 TVS to 9 volt source for ESD issues.
 - 11/13/18
 - Rev D3C: Fixed unconnected ground pad on regulator due to imported design rules.